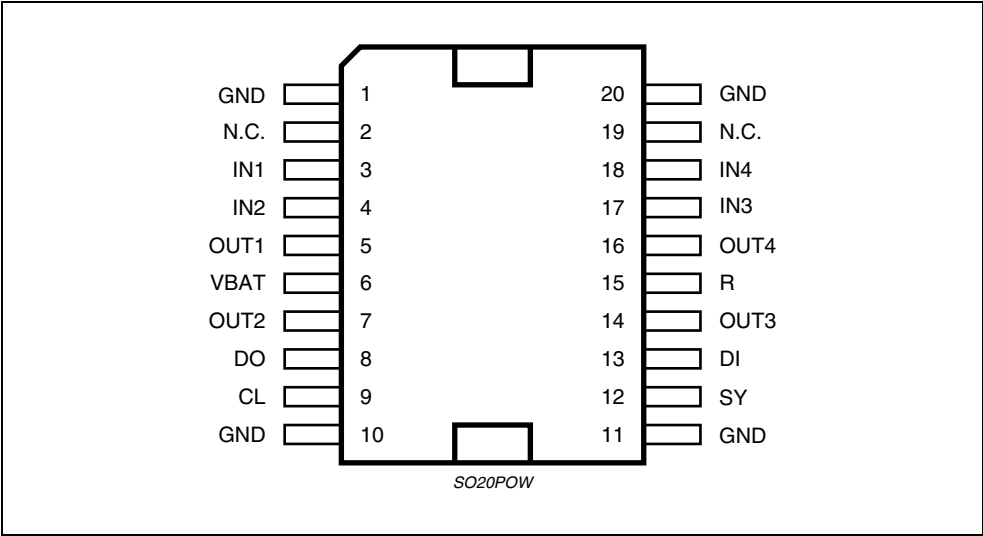


PIN CONNECTION (Top view)



PIN FUNCTION

N°	Pin	Function
1, 10, 11, 20	GND	Ground
2, 19	N.C.	Not Connected
3	IN1	Input 1
4	IN2	Input 2
5	OUT1	Output 1
6	VBAT	Supply Voltage
7	OUT2	Output 2
8	DO	Serial Data Out
9	CL	Clock
12	SY	Synchronization
13	DI	Serial Data In
14	OUT3	Output 3
15	R	Reset
16	OUT4	Output 4
17	IN3	Input 3
18	IN4	Input 4

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
T_{STG}	Storage Temperature	-55 to 150	°C
T_J	Operating Junction Temperature	-40 to 150	°C
V_{BAT}	DC Supply Voltage	-2 to 30	V
V_{BATr}	Transient Supply Voltage; $t < 400ms$	40	V
V_{OUT}	Output Voltage	65	V
V_{OUTr}	Transient Output Voltage; during clamping	78	V
E_{CL}	Output Clamping energy; repetition rate $< 100\text{ Hz}$	10	mJ
$-I_{OUT}$	Output reverse current	2	A
$V_R, V_{INi}, V_{DI}, V_{CLVSy}$	Control Input voltage	-0.3 to 6.5	V
V_{DO}	Control Output voltage	-0.3 to 6.5	V

THERMAL DATA

Symbol	Parameter	Value	Unit
$R_{th\ j-case}$	Thermal Resistance Junction to Case	2.5	°C/W

ELECTRICAL CHARACTERISTICS (6.5V $< V_{BAT} < 25V$, -40 $< T_J < 150^\circ\text{C}$)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Supply Voltage						
V _{BATU}	Turn on threshold voltage		2.0		4.7	V
I _{BAT}	Supply current	V _{BAT} = 14V V _{OUTi} > 0V	4	10	15	mA
Output stage						
R _{DSOn}	On resistance	V _{BAT} = 14V T _J = 25°C; I _{out} = 1A V _{BAT} = 14V T _J = 150°C; I _{out} = 1A			500 850	mΩ mΩ
V _{CL}	Clamping voltage, inductive load	I _{out} = 0.5 A	63	70	76	V
I _{OUTi}	Over current shutdown (Shutdown latch resets with pos. slope at I _{NI})	T _J = -40°C T _J = 25°C T _J = 150°C	3.0 2.5 2.2		4.3 3.7 3.5	A A A
Output leakage current see: Open load diagnostic current						

ELECTRICAL CHARACTERISTICS (continued)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Logic Inputs IN1...IN4, SY, CL, DI, R						
V _{IN1LH} V _{SYLH} V _{CLLH} V _{RLH} V _{D1LH}	Input High level		3.5		6.5	V
V _{IN1HL} V _{SYHL} V _{CLHL} V _{RHL} V _{D1HL}	Input Low level		-0.3		1.5	V
V _{IN1h} V _{SYh} V _{CLh} V _{Rh} V _{D1h}	Hysteresis		0.2		1	V
- I _{IN1} - I _{SY} - I _{CL} - I _R	Input current IN1 ... IN4, SY, CL, R (Internal pull up current source)	V _{IN1} = 0V V _{SY} = 0V V _{CL} = 0V V _R = 0V	10 10	40	120 80	μA
- I _{D1}	Input current DI (Internal pull up current source)	V _{D1} = 0V	120	220	250	μA
Timing						
t _{don}	Turn on delay			7.5		μs
t _{doff}	Turn off delay			7.5		μs
S _{on}	Switch on slew rate			10		V/μs
S _{off}	Switch off slew rate			15		V/μs
t _{oc}	Over current detection time			0.5		μs
t _v	Open load filtering time		60	100	200	μs
t _v	Short to GND filtering time		60	100	200	μs
f _{CL}	Serial clock frequency		0		500	kHz
t _{VDV}	DO: Data valid time		0.03		1	μs
t _{VSET}	DI: Data settling time		0.5			μs
t _{VHOLD}	DI: Data hold time		0			μs
Diagnostic						
V _{BATDU}	Under voltage threshold		4.7		7.5	V
Serial Data output (External pull up required)						
V _{DO}	Data output low voltage	I _{DO} < 1.6mA 7.5V < V _{BAT} < 22V	0		0.45	V
I _{DO}	Data output leakage current				10	μA

ELECTRICAL CHARACTERISTICS (continued)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Output voltage monitoring Output off						
V_{OL}	Open load threshold voltage (fault detected if $V_{OUTi} < V_{OL}$)	$7.5V < V_{BAT} < 22V$		$2/3V_{BAT}$		
V_{SG}	Short to GND threshold voltage (fault detected if $V_{OUTi} < V_{SG}$)	$7.5V < V_{BAT} < 22V$		$1/3V_{BAT}$		
Open load diagnostic current Output off						
	Open load output voltage	$I_{OUT} = 0\text{ A}$ $V_{INI} = 5V$ $7.5V < V_{BAT} < 22V$		$1/2V_{BAT}$		
$-I_{OUTi}$	Output current	$V_{OUT} = 1V$ $V_{INI} = 5V$	50	100	150	μA
I_{OUTi}	Output current	$V_{OUT} = V_{BAT}$ $V_{INI} = 5V$ $7.5V < V_{BAT} < 22V$	200	320	500	μA
Overload Diagnostic						
	Over temperature diagnostic	T_J		175		$^{\circ}\text{C}$
I_{OUTi}	Over current	$T_J = -40^{\circ}\text{C}$	3.0		4.3	A
		$T_J = 25^{\circ}\text{C}$	2.5		3.7	A
		$T_J = 150^{\circ}\text{C}$	2.2		3.5	A

Figure 1. Typical Timing Diagram for Serial Diagnostic

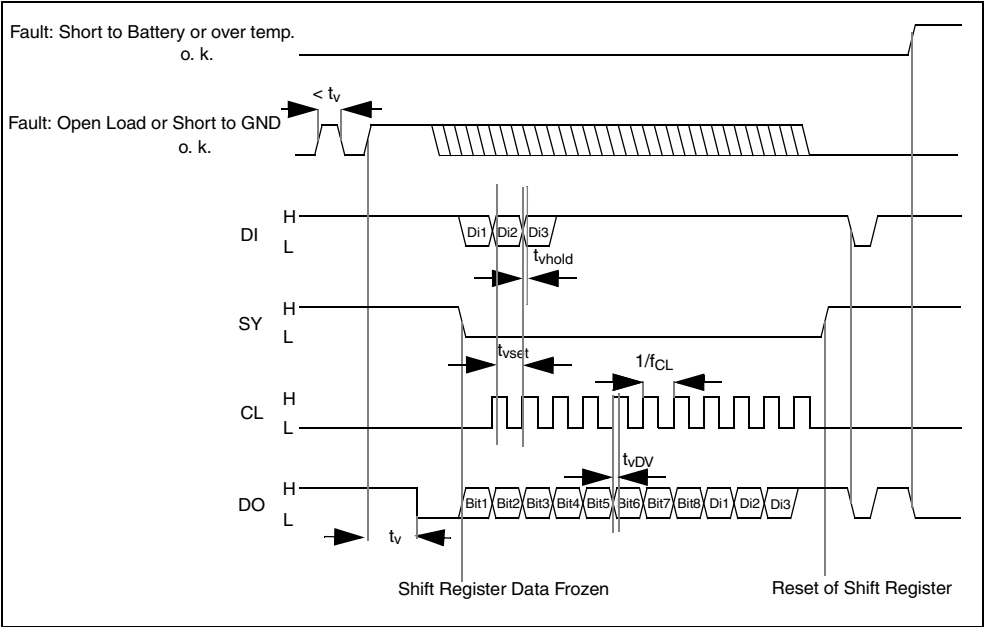


Figure 2. Serial Interface Error Coding

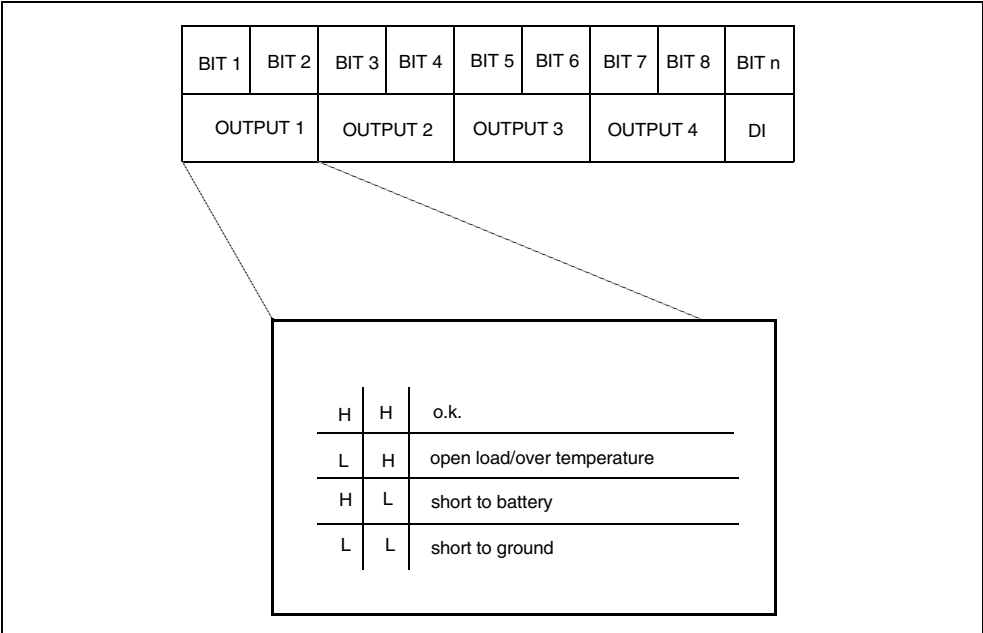


Figure 3. Output voltage TIMING for inductive load

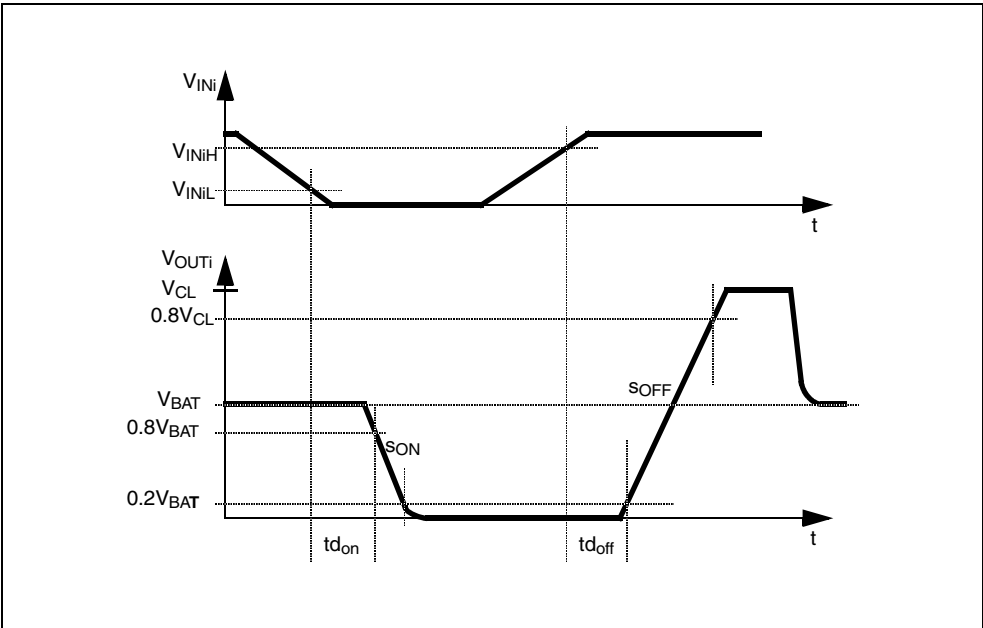
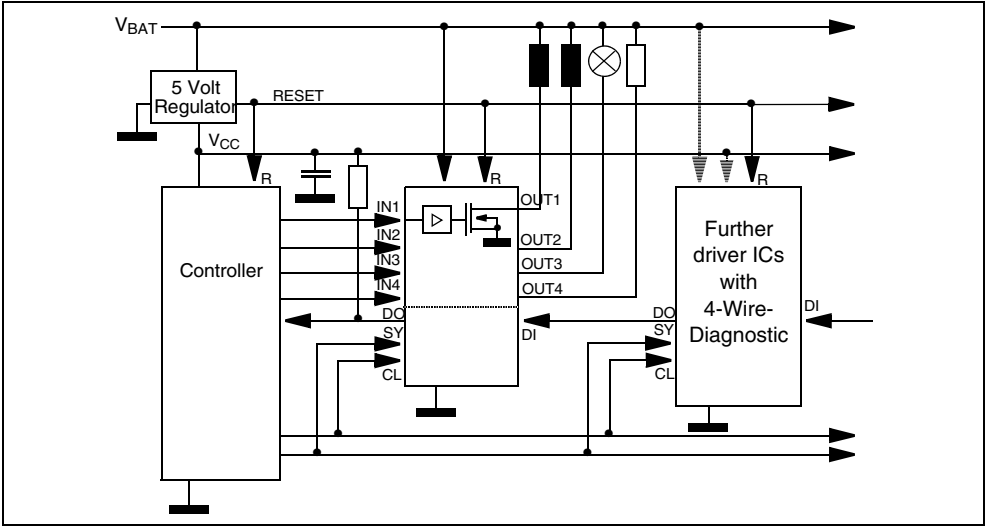
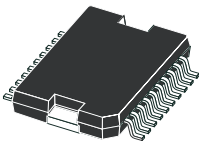


Figure 4. Application Circuit



OUTLINE AND
MECHANICAL DATA

Weight: 1.9gr

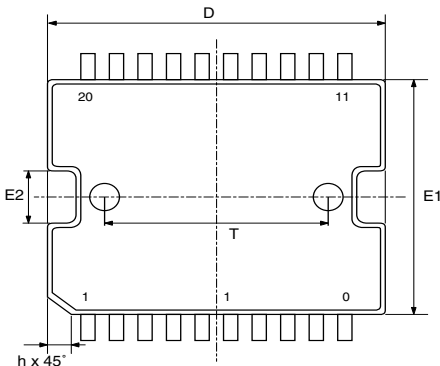
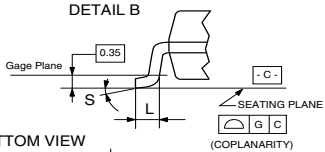
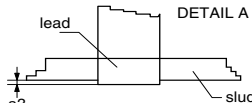
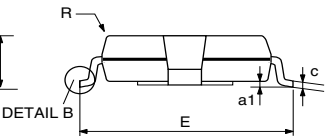
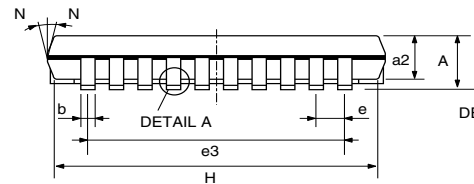


JEDEC MO-166

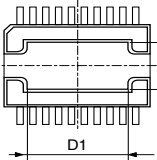
PowerSO-20

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			3.6			0.142
a1	0.1		0.3	0.004		0.012
a2			3.3			0.130
a3	0		0.1	0.000		0.004
b	0.4		0.53	0.016		0.021
c	0.23		0.32	0.009		0.013
D (1)	15.8		16	0.622		0.630
D1 (2)	9.4		9.8	0.370		0.386
E	13.9		14.5	0.547		0.570
e		1.27			0.050	
e3		11.43			0.450	
E1 (1)	10.9		11.1	0.429		0.437
E2			2.9			0.114
E3	5.8		6.2	0.228		0.244
G	0		0.1	0.000		0.004
H	15.5		15.9	0.610		0.626
h			1.1			0.043
L	0.8		1.1	0.031		0.043
N	8°(typ.)					
S	8°(max.)					
T		10			0.394	

- (1) "D and E1" do not include mold flash or protusions.
- Mold flash or protusions shall not exceed 0.15mm (0.006")
- Critical dimensions: "E", "G" and "a3".
(2) For subcontractors, the limit is the one quoted in jedec MO-166



BOTTOM VIEW



PSO20MEC

0056635 I



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